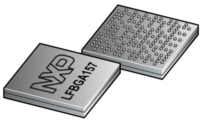
SOT1919-1

LFBGA157, low profile, fine-pitch ball grid array package, 157 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.25 mm body

12 June 2025 | Package information



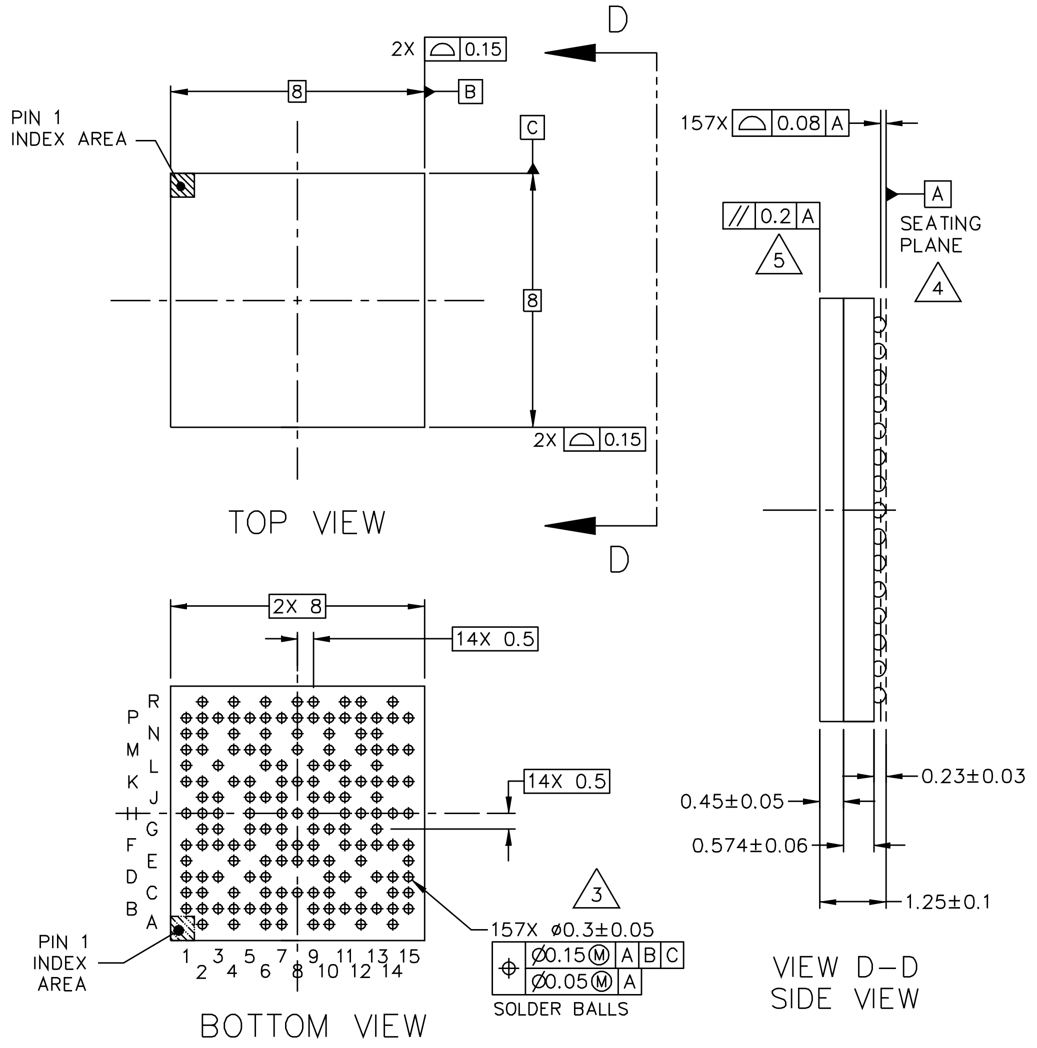
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA157
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	12-06-2017
Manufacturer package code	98ASA01073D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.85	8	8.15	mm
package width	7.85	8	8.15	mm
package height	1.15	1.25	1.35	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	157	-	

2 Package outline



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TITLE: FCPBGA, MOLDED ARRAY, 8 X 8 X 1.25 PKG, 0.5 MM PITCH, 157 I/O	DOCUMENT NO: 98ASA01073D	REV: A
	STANDARD: NON–JEDEC	
	SOT1919–1	12 JUN 2017

Figure 1. Package outline LFBGA157 (SOT1919-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
5. MAXIMUM SOLDER BUMP SHAPE MEASURED PARALLEL TO DATUM A.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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Figure 2. Package outline note LFBGA157 (SOT1919-1)

3 Legal information

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